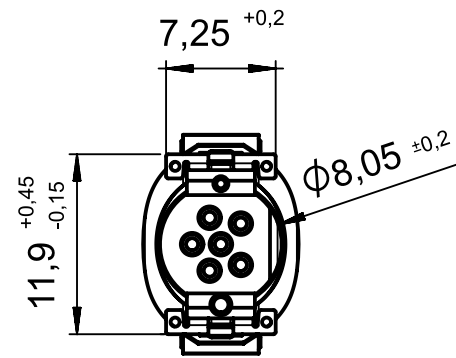
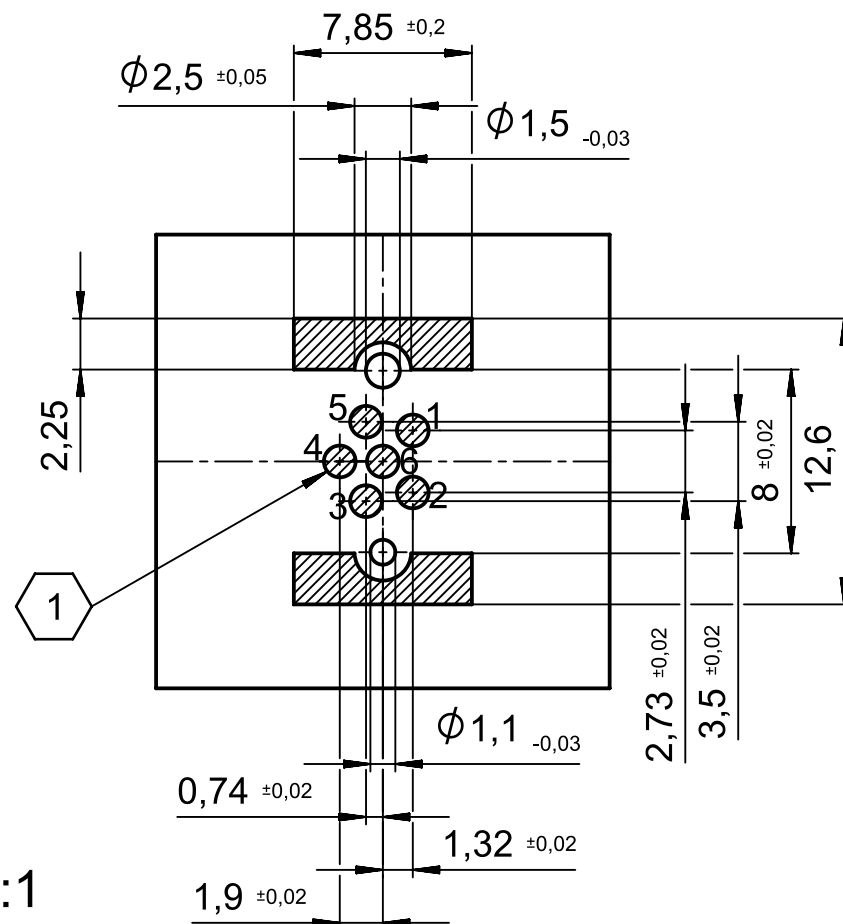


Transfer or duplication of this document as well as the utilisation or communication of its content are not permitted unless express consent is granted. Violations give rise to claims for damages. All rights reserved in case of patent, utility model or design patent registrations. Tolerance specifications do not include clearances inherent in the design.

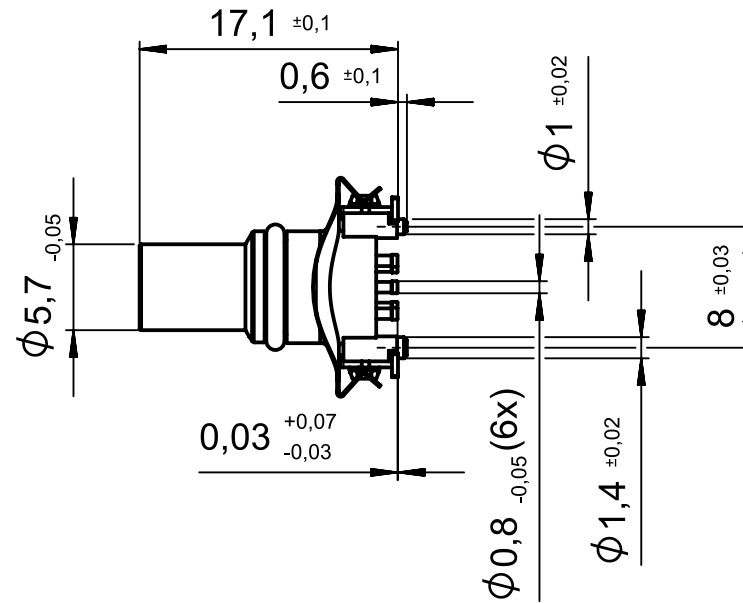
Weitergabe sowie Vervielfältigung dieses Dokuments, Verwertung und Mitteilung seines Inhalts sind verboten, soweit nicht ausdrücklich gestattet. Zuwiderhandlungen verpflichten zu Schadenersatz. Alle Rechte für den Fall der Patent-, Gebrauchsmuster- oder Designeintragung vorbehalten. Bauartbedingtes Spiel ist in den Toleranzangaben nicht berücksichtigt.



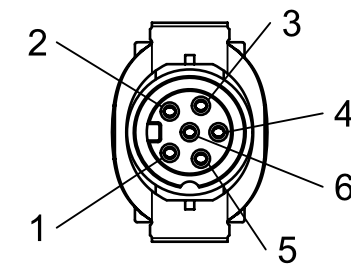
PCB-layout
(advice)



3:1



socket face female



Coplanarity of all contacts and anchor plate  0.1

Recommended solder paste thickness 150µm

 Further information on soldering process and recommended layout, see brochure "Connectors for SMT production"

- EN ISO 291 23/50

 DIN A3		document-no. / ri 102992607 / 00	article-no. / ri 1412238 / 06	scale 2:1	- Simplified representation - Linear dimensions (mm)
		date 2025-11-11	document-type TECDOC 2D-Productdrawing		
		description SACC-CIP-M8FS-6P SMD SH T			
page	1	of	1		

A3